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U.S. Patent Application No. 10/791,014

OLP Reply to Office Action of August 17, 2005

Attorney Docket No. TSMC2000-488 / 24061.596 Customer No. 42717

بح NOV 15 2005 <sup>5</sup>

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Chung-Shi Liu et al.

g-Shi Liu et al.

Serial No.: 10/791,014

Filed: March 2, 2004

For: PREVENTION OF POST CMP

DEFECTS IN CU/FSG PROCESS

Group Art Unit: 2826

Examiner: Fetsum Abraham

Commissioner for Patents Mail Stop Amendment P.O. Box 1450 Alexandria, VA 22313-1450

## **AMENDMENT**

Sir:

In response to the Office action of August 17, 2005, please amend the above-identified application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks begin on page 8 of this paper.